nexperia

Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Suppl	ier	User Part Number							
Nexper	ia B.V.	74HC112PW	74HC112PW						
Fur Pro	Description: Dual J-K flip-flon nction Family: HC(T) process family: Super micron ckage family: TSSOP	p with set and reset; negat	ive-edge trigger						
JESD4	17 Test	Test Conditions	Duration	# Lots	# Quantity	# Rejects			
# 1	TEST Pre- and Post-Stress Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below			
# 2	PC Preconditioning	JESD22-A113 MSL 1	N/A	863	73980	0			
# 5a	HTOL EFR High Temperature Operating Life Extrinsic	JESD22-A108 Tj = 150°C V _{CCMAX} \leq V \leq 1.2*V _{CCMAX}	48 hours or 168 hours	58	23674	0			
# 5b	HTOL IFR High Temperature Operating Life Intrinsic	JESD22-A108 Tj = 150°C V _{CCMAX} \leq V \leq 1.2*V _{CCMAX}	≥500 hours	55	2997	0			
# 7	TC Temperature Cycling	JESD22-A104 -65 °C to 150°C	≥500 cycles	478	37734	0			
#9	uHAST / HAST unbiased or biased High Accelerated Stress Test	JESD22-A101 Tamb = 130 °C, RH = 85%, V = V _{CCMAX}	96 hours	462	36246	0			

Calculation of PPM, FIT and MTTF

Test considered for PPM calculation: High Temperature Operating LifeTest Extrinsic (HTOL EFR, Test # 5a above) Test considered for FIT and MTTF calculations: High Temperature Operating LifeTest Intrinsic(HTOL IFR, Test # 5b above)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Product Family	Package Family	Quantity	Rejects	Extrinsic Failure Rate (PPM)	Intrinsic Failure Rate (FIT)	MTTF (hrs)
HC(T)	TSSOP	2997	0	39	1.3	8.12 E+08

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.